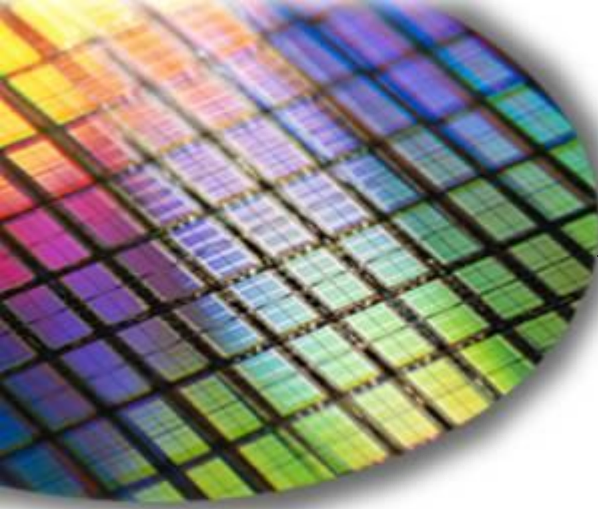


The World Leader in High Performance Signal Processing Solutions

ADSP-21369 Package Change
PCN# 17_0163

August 2017

ANALOG DEVICES

Current Package Drawing (SBGA)

256-Ball Ball Grid Array, Thermally Enhanced [BGA_ED]
(BP-256)
Dimensions shown in millimeters

27.00
BSC SQ

BALL A1
INDICATOR

TOP VIEW

A1 CORNER
INDEX AREA

20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1

A B C D E F G H J K L M N P R T U V W Y

24.13
BSC SQ

1.27
BSC

BOTTOM
VIEW

DETAIL A

DETAIL A

1.70 MAX

0.10 MIN

1.00
0.80
0.60

0.70
0.60
0.50

COPLANARITY
0.20

0.90
0.75
0.60
BALL DIAMETER

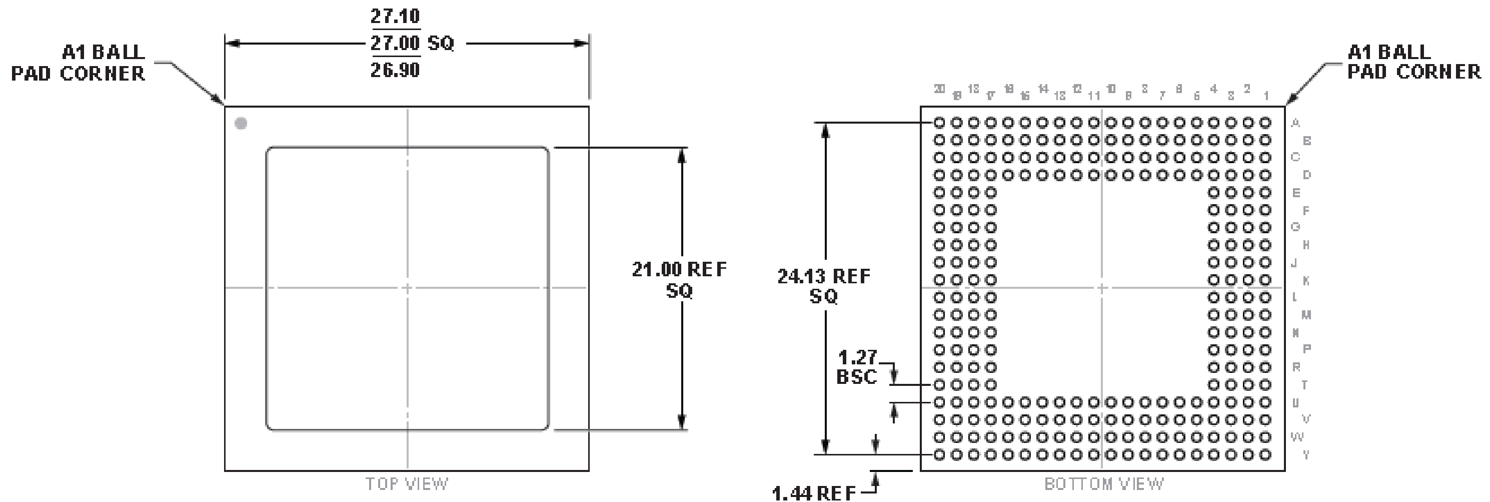
0.25 MIN
(4×)

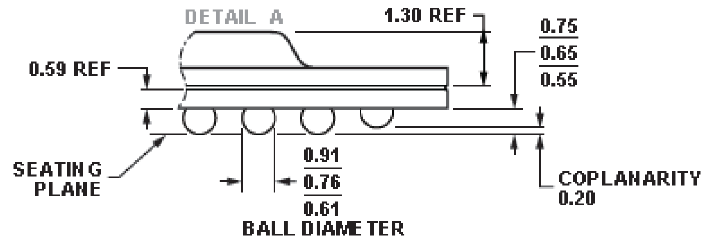
SEATING
PLANE

ANALOG
DEVICES

New Package Drawing (Flip-Chip BGA)

256-Ball Ball Grid Array, Thermally Enhanced [BGA_ED]
(BP-256-2)
Dimensions shown in millimeters





ANALOG DEVICES

Significant Differences

- **Package thickness:**
  - Current Pkg.: 1.70mm max.
  - New Package: 2.84mm max.

Qualification Results Summary of ADSP-21369 in 256-BGA_ED Package at AMKOR

QUALIFICATION RESULTS			
TEST	**SPECIFICATION**	**SAMPLE SIZE**	**RESULTS**
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	**3 x 32**	**Pass**
Temperature/Humidity/Bias (THB)*	JEDEC *JESD22-A101*	**3 x 32**	**Pass**
High Temperature Storage Life (HTSL)	JEDEC *JESD22-A103*	**1 x 32**	**Pass**
Solder Heat Resistance (SHR)*	JEDEC/IPC *J-STD-020*	**3 x 11**	**Pass**
Electrostatic Discharge *Field-Induced Charged Device Model*	JEDEC *JESD22-C101*	**3/voltage**	**Pass 1000V**

*Preconditioned per JEDEC/IPC J-STD-020